



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

DN 51343

In re application of:
Seita et al.

Serial No.: 10/027,919

Filed: December 20, 2001

: Group Art Unit: 1753

For: ELECTROLYTIC COPPER PLATING
SOLUTION AND METHOD FOR
CONTROLLING THE SAME

: Examiner: Edna Wong

AMENDMENT

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

In response to the Official Action mailed on June 25, 2004, Applicants request entry of the following amendments and remarks.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks begin on page 8 of this paper.